

Title (en)

CIRCUIT BOARD ARRANGEMENT AND METHOD FOR PRODUCING A CIRCUIT BOARD ARRANGEMENT

Title (de)

LEITERPLATTENANORDNUNG UND VERFAHREN ZUM HERSTELLEN EINER LEITERPLATTENANORDNUNG

Title (fr)

SYSTÈME DE CARTE DE CIRCUITS IMPRIMÉS ET PROCÉDÉ DE FABRICATION D'UN SYSTÈME DE CARTE DE CIRCUITS IMPRIMÉS

Publication

EP 4103915 A1 20221221 (DE)

Application

EP 21709346 A 20210210

Priority

- DE 102020201674 A 20200211
- EP 2021053138 W 20210210

Abstract (en)

[origin: WO2021160639A1] The present invention relates to a circuit board arrangement (100) and to a method for producing a circuit board arrangement (100) for a device for ascertaining the fill level and/or the quality and the temperature of a fluid (12) of an internal combustion engine. The circuit board arrangement (100) has a first region (110), to which electronics (112) of the device are attached, a plate-like second region (120), which is arranged at a predetermined angle (150) with respect to the first region (110) and to which a temperature sensor (122) for ascertaining the temperature of the fluid (12) is attached, and a support element (140), which is connected to the first region (110) and to the second region (120) and which is designed to fix the first region (110) and the second region (120) at the predetermined angle (150) with respect to one another.

IPC 8 full level

G01F 23/00 (2022.01); **G01F 23/296** (2022.01); **G01N 29/024** (2006.01); **G01N 29/22** (2006.01); **G01N 29/24** (2006.01); **G01S 15/88** (2006.01); **H05K 1/02** (2006.01); **H05K 3/28** (2006.01)

CPC (source: EP)

G01F 23/2962 (2013.01); **G01F 23/804** (2022.01); **G01N 29/024** (2013.01); **G01N 29/222** (2013.01); **G01N 29/223** (2013.01); **G01N 29/2437** (2013.01); **H05K 1/0278** (2013.01); **G01N 2291/022** (2013.01); **G01N 2291/0226** (2013.01); **G01N 2291/0258** (2013.01); **G01N 2291/02809** (2013.01); **G01N 2291/02818** (2013.01); **H05K 1/0283** (2013.01); **H05K 3/284** (2013.01); **H05K 2201/046** (2013.01); **H05K 2201/09972** (2013.01); **H05K 2201/10151** (2013.01); **H05K 2203/1327** (2013.01)

Citation (search report)

See references of WO 2021160639A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

Designated validation state (EPC)

KH MA MD TN

DOCDB simple family (publication)

DE 102020201674 A1 20210812; CN 115038940 A 20220909; EP 4103915 A1 20221221; WO 2021160639 A1 20210819

DOCDB simple family (application)

DE 102020201674 A 20200211; CN 202180014119 A 20210210; EP 2021053138 W 20210210; EP 21709346 A 20210210